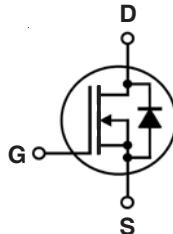
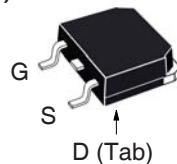
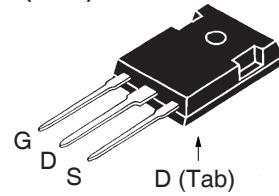


**Depletion Mode  
MOSFET**
**IXTT16N10D2  
IXTH16N10D2**
 $V_{DSX} = 100V$   
 $I_{D(on)} \geq 16A$   
 $R_{DS(on)} \leq 64m\Omega$ 
**N-Channel**

**TO-268 (IXTT)**

**TO-247 (IXTH)**

G = Gate      D = Drain  
S = Source      Tab = Drain

Symbol	Test Conditions	Maximum Ratings	
$V_{DSX}$	$T_J = 25^\circ C$ to $175^\circ C$	100	V
$V_{DGX}$	$T_J = 25^\circ C$ to $175^\circ C$ , $R_{GS} = 1M\Omega$	100	V
$V_{GSX}$	Continuous	$\pm 20$	V
$V_{GSM}$	Transient	$\pm 30$	V
$P_D$	$T_c = 25^\circ C$	830	W
$T_J$		- 55 ... +175	$^\circ C$
$T_{JM}$		175	$^\circ C$
$T_{stg}$		- 55 ... +175	$^\circ C$
$T_L$	Maximum Lead Temperature for Soldering	300	$^\circ C$
$T_{SOLD}$	1.6 mm (0.062in.) from Case for 10s	260	$^\circ C$
$M_d$	Mounting Torque (TO-247)	1.13 / 10	Nm/lb.in
<b>Weight</b>	TO-268 TO-247	4 6	g

Symbol	Test Conditions ( $T_J = 25^\circ C$ , Unless Otherwise Specified)	Characteristic Values		
		Min.	Typ.	Max.
$BV_{DSX}$	$V_{GS} = - 5V$ , $I_D = 250\mu A$	100		V
$V_{GS(off)}$	$V_{DS} = 25V$ , $I_D = 4mA$	- 2.0		- 4.5 V
$I_{GSX}$	$V_{GS} = \pm 20V$ , $V_{DS} = 0V$			$\pm 100 \mu A$
$I_{DSX(off)}$	$V_{DS} = V_{DSX}$ , $V_{GS} = - 5V$ $T_J = 150^\circ C$			5 $\mu A$ 250 $\mu A$
$R_{DS(on)}$	$V_{GS} = 0V$ , $I_D = 8A$ , Note 1			64 $m\Omega$
$I_{D(on)}$	$V_{GS} = 0V$ , $V_{DS} = 25V$ , Note 1	16		A

**Features**

- Normally ON Mode
- International Standard Packages
- Molding Epoxies Meet UL 94 V-0 Flammability Classification

**Advantages**

- Easy to Mount
- Space Savings
- High Power Density

**Applications**

- Audio Amplifiers
- Start-up Circuits
- Protection Circuits
- Ramp Generators
- Current Regulators
- Active Loads

Symbol	Test Conditions ( $T_J = 25^\circ\text{C}$ , Unless Otherwise Specified)	Characteristic Values		
		Min.	Typ.	Max.
$g_{fs}$	$V_{DS} = 20\text{V}$ , $I_D = 8\text{A}$ , Note 1	7	11	S
$C_{iss}$ $C_{oss}$ $C_{rss}$	$V_{GS} = -10\text{V}$ , $V_{DS} = 25\text{V}$ , $f = 1\text{MHz}$	5700	pF	
		1980	pF	
		940	pF	
$t_{d(on)}$ $t_r$ $t_{d(off)}$ $t_f$	<b>Resistive Switching Times</b> $V_{GS} = \pm 5\text{V}$ , $V_{DS} = 50\text{V}$ , $I_D = 8\text{A}$ $R_G = 3.3\Omega$ (External)	45	ns	
		43	ns	
		340	ns	
		70	ns	
$Q_{g(on)}$ $Q_{gs}$ $Q_{gd}$	$V_{GS} = \pm 5\text{V}$ , $V_{DS} = 50\text{V}$ , $I_D = 8\text{A}$	225	nC	
		22	nC	
		126	nC	
$R_{thJC}$ $R_{thCS}$	TO-247	0.21	0.18 $^\circ\text{C}/\text{W}$ $^\circ\text{C}/\text{W}$	

### Safe-Operating-Area Specification

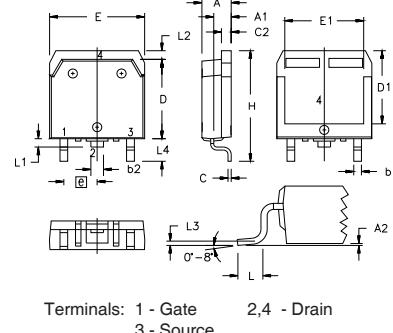
Symbol	Test Conditions	Characteristic Values		
		Min.	Typ.	Max.
SOA	$V_{DS} = 100\text{V}$ , $I_D = 5.6\text{A}$ , $T_C = 75^\circ\text{C}$ , $tp = 5\text{s}$	556		W

### Source-Drain Diode

Symbol	Test Conditions ( $T_J = 25^\circ\text{C}$ , Unless Otherwise Specified)	Characteristic Values		
		Min.	Typ.	Max.
$V_{SD}$	$I_F = 16\text{A}$ , $V_{GS} = -10\text{V}$ , Note 1	0.80	1.30	V
$t_{rr}$ $I_{RM}$ $Q_{RM}$	$I_F = 8\text{A}$ , $-di/dt = 100\text{A}/\mu\text{s}$ $V_R = 100\text{V}$ , $V_{GS} = -10\text{V}$	205	ns	
		8.50	A	
		0.88	$\mu\text{C}$	

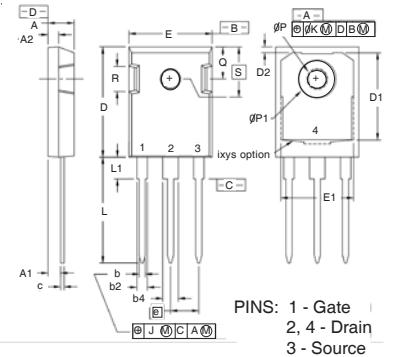
Note 1. Pulse test,  $t \leq 300\mu\text{s}$ , duty cycle,  $d \leq 2\%$ .

### TO-268 Outline



SYM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	.193	.201	4.90	5.10
A1	.106	.114	2.70	2.90
A2	.001	.010	0.02	0.25
b	.045	.057	1.15	1.45
b2	.075	.083	1.90	2.10
C	.016	.026	0.40	0.65
C2	.057	.063	1.45	1.60
D	.543	.551	13.80	14.00
D1	.488	.500	12.40	12.70
E	.624	.632	15.85	16.05
E1	.524	.535	13.30	13.60
e	.215	BSC	5.45	BSC
H	.736	.752	18.70	19.10
L	.094	.106	2.40	2.70
L1	.047	.055	1.20	1.40
L2	.039	.045	1.00	1.15
L3	.010	BSC	0.25	BSC
L4	.150	.161	3.80	4.10

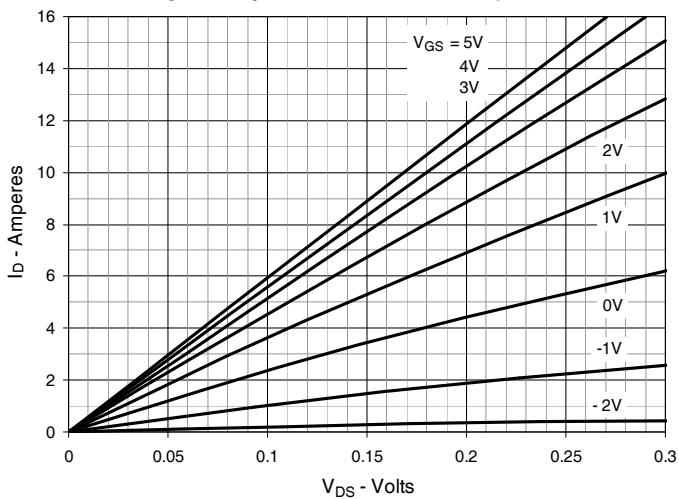
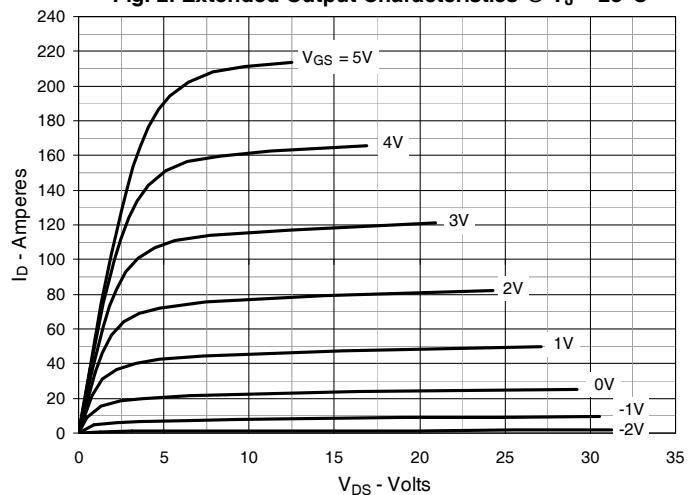
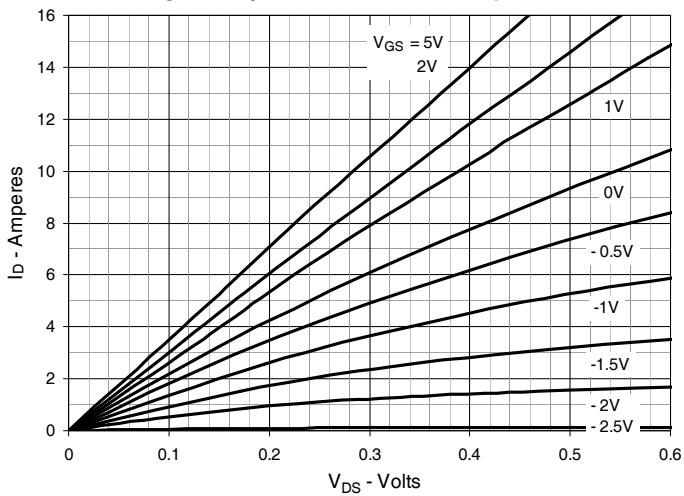
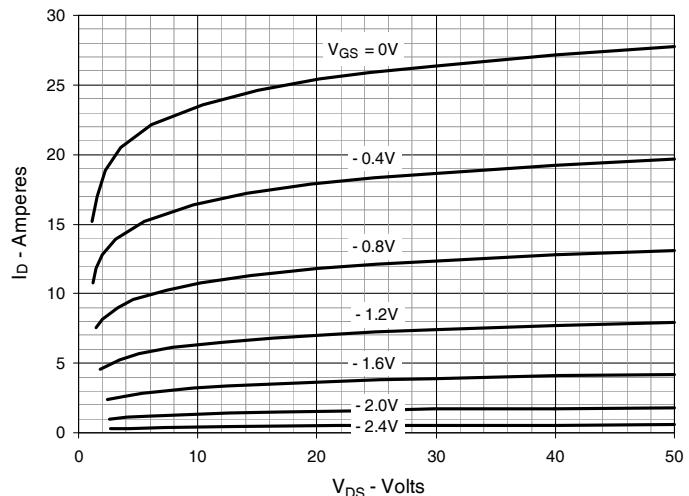
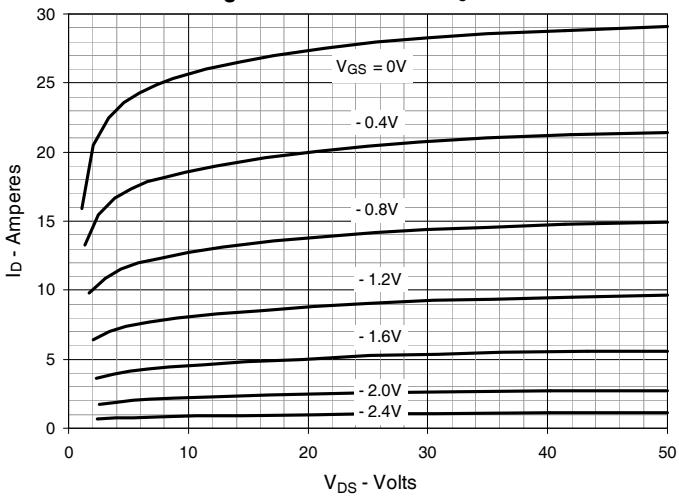
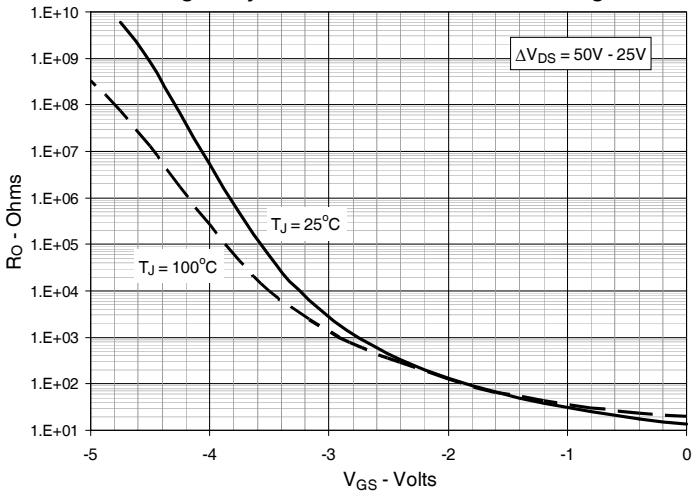
### TO-247 Outline

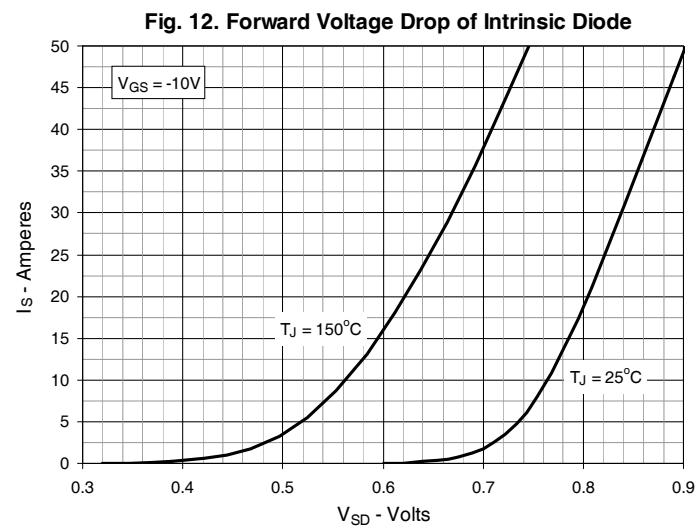
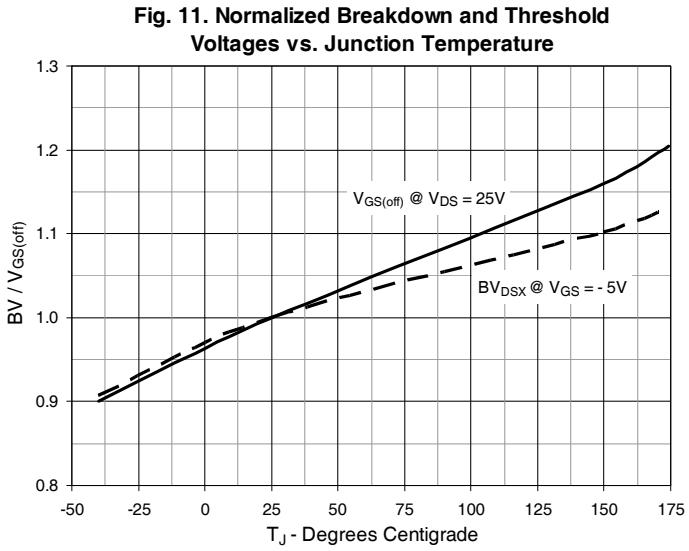
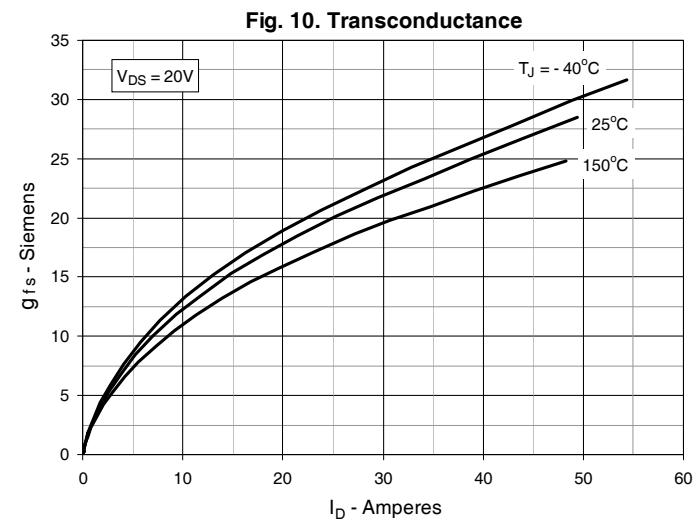
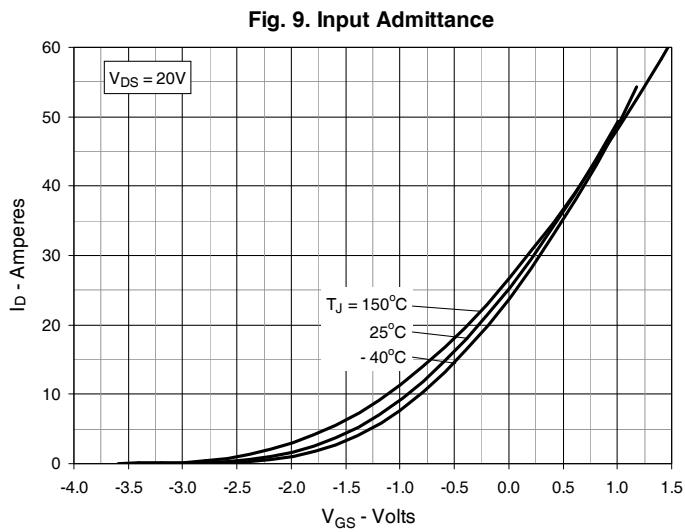
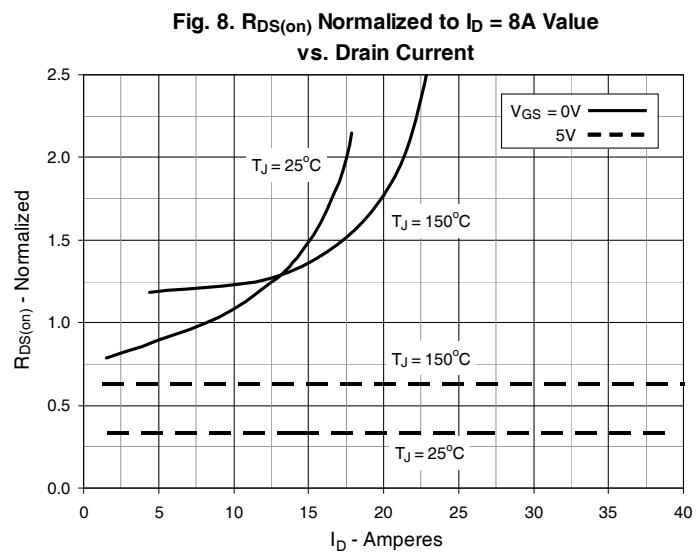
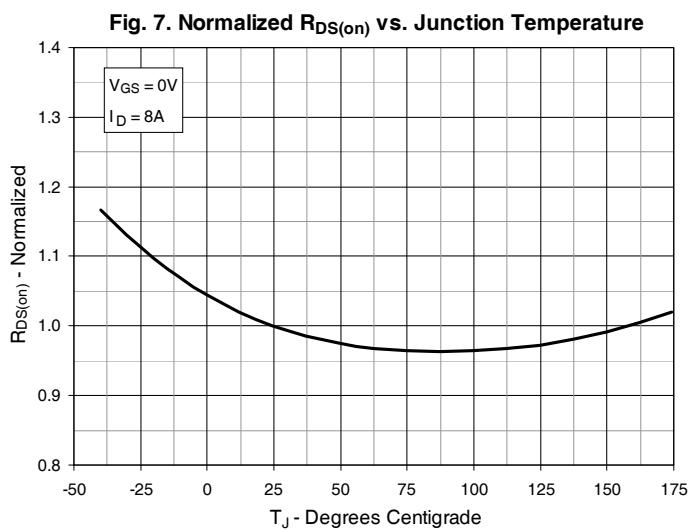


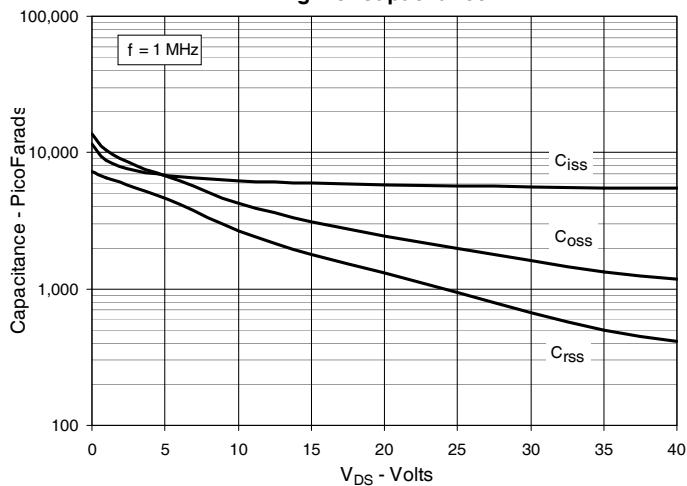
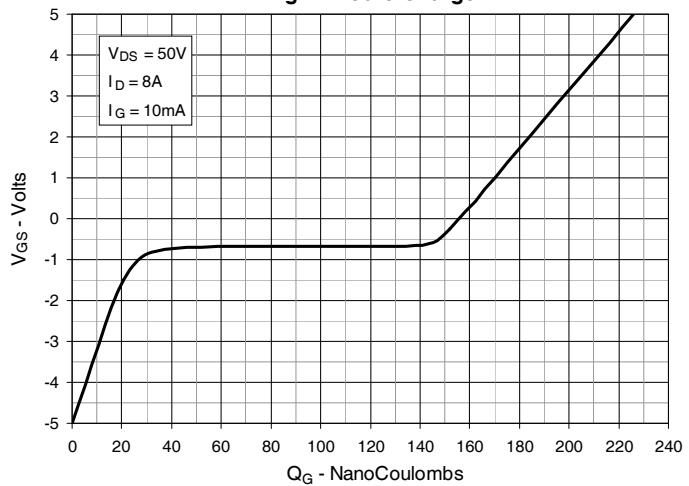
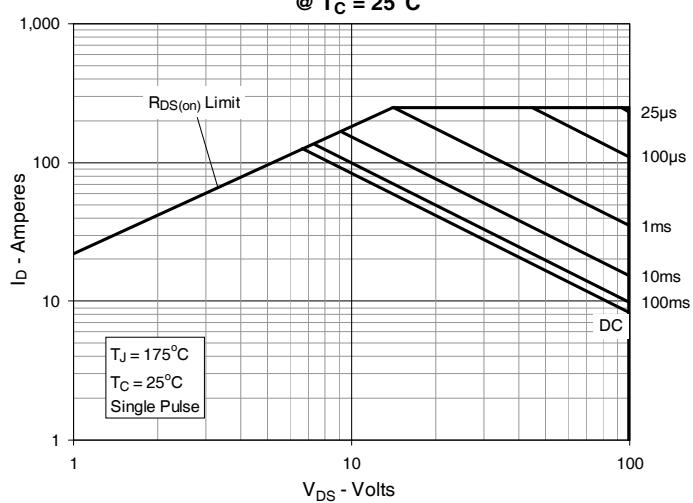
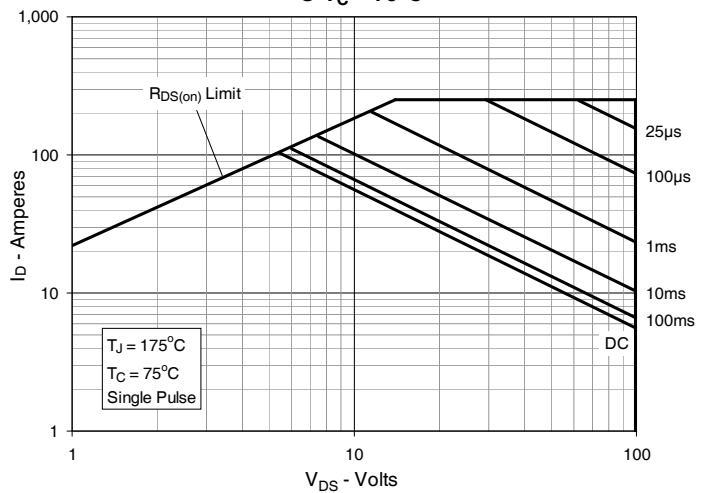
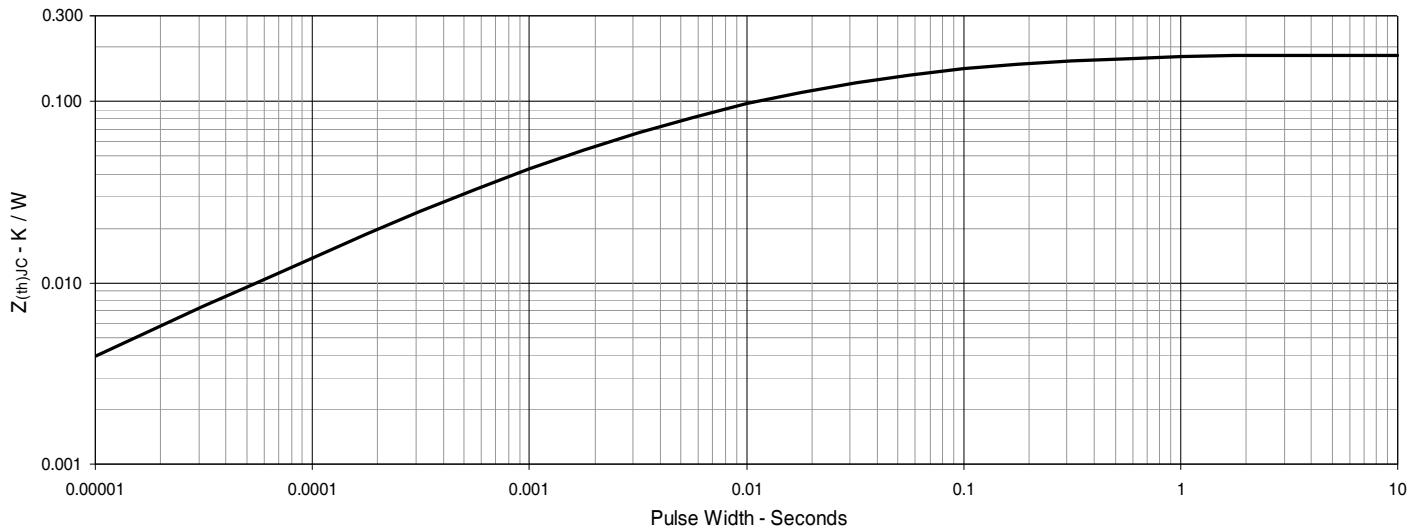
SYM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	.190	.205	4.83	5.21
A1	.090	.100	2.29	2.54
A2	.075	.085	1.91	2.16
b	.045	.055	1.14	1.40
b2	.075	.087	1.91	2.20
b4	.115	.126	2.92	3.20
C	.024	.031	0.61	0.80
D	.819	.840	20.80	21.34
D1	.650	.690	16.51	17.53
D2	.035	.050	0.89	1.27
E	.620	.635	15.75	16.13
E1	.545	.565	13.84	14.35
e	.215	BSC	5.45	BSC
J	--	.010	--	0.25
K	--	.025	--	0.64
L	.780	.810	19.81	20.57
L1	.150	.170	3.81	4.32
ØP	.140	.144	3.55	3.65
ØP1	.275	.290	6.99	7.37
Q	.220	.244	5.59	6.20
R	.170	.190	4.32	4.83
S	.242	BSC	6.15	BSC

IXYS Reserves the Right to Change Limits, Test Conditions, and Dimensions.

IXYS MOSFETs and IGBTs are covered by one or more of the following U.S. patents: 4,835,592, 4,931,844, 5,049,961, 5,237,481, 6,162,665, 6,404,065 B1, 6,683,344, 6,727,585, 7,005,734 B2, 7,157,338B2, 4,860,072, 5,017,508, 5,063,307, 5,381,025, 6,259,123 B1, 6,534,343, 6,710,405 B2, 6,759,692, 7,063,975 B2, 4,881,106, 5,034,796, 5,187,117, 5,486,715, 6,306,728 B1, 6,583,505, 6,710,463, 6,771,478 B2, 7,071,537

**Fig. 1. Output Characteristics @  $T_J = 25^\circ\text{C}$** 

**Fig. 2. Extended Output Characteristics @  $T_J = 25^\circ\text{C}$** 

**Fig. 3. Output Characteristics @  $T_J = 150^\circ\text{C}$** 

**Fig. 4. Drain Current @  $T_J = 25^\circ\text{C}$** 

**Fig. 5. Drain Current @  $T_J = 100^\circ\text{C}$** 

**Fig. 6. Dynamic Resistance vs. Gate Voltage**




**Fig. 13. Capacitance**

**Fig. 14. Gate Charge**

**Fig. 15. Forward-Bias Safe Operating Area  
@  $T_C = 25^\circ\text{C}$** 

**Fig. 16. Forward-Bias Safe Operating Area  
@  $T_C = 75^\circ\text{C}$** 

**Fig. 17. Maximum Transient Thermal Impedance**




---

Disclaimer Notice - Information furnished is believed to be accurate and reliable. However, users should independently evaluate the suitability of and test each product selected for their own applications. Littelfuse products are not designed for, and may not be used in, all applications. Read complete Disclaimer Notice at [www.littelfuse.com/disclaimer-electronics](http://www.littelfuse.com/disclaimer-electronics).